

## Designer's Data Sheet

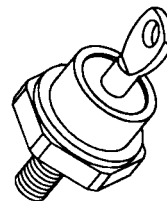
### FEATURES:

- Ultra Fast Recovery: 50 nsec Maximum
- Radiation Tolerant
- Very Low Forward Voltage Drop
- Hermetically Sealed
- Single Chip Construction
- 175°C Operating Temperature
- For High Efficiency Applications
- TX, TXV and Space Level Screening Available

**SDR405  
thru  
SDR415**

**50 AMP  
50-150 VOLTS  
50 nsec  
ULTRA FAST  
RECTIFIER**

DO-5



### MAXIMUM RATINGS

RATING	SYMBOL	VALUE	UNIT
Peak Repetitive Reverse and DC Blocking Voltage  SDR405 SDR407 SDR410 SDR412 SDR415	VRRM  VRWM  VR	50 70 100 125 150	Volts
Average Rectified Forward Current (Resistive Load, 60Hz, Sine Wave, TA=25°C)	IO	50	Amps
Peak Surge Current (8.3 ms Pulse, Half Sine Wave, TA=25°C)	IFSM	450	Amps
Operating and storage temperature	Top & Tstg	-65 to +175	°C
Maximum Thermal Resistance Junction to Case	RθJC	1.0	°C/W

NOTE: All specifications are subject to change without notification.  
SCD's for these devices should be reviewed by SSDI prior to release.

DATA SHEET #: RU0039 A

RMD

# SDR405 thru SDR415

PRELIMINARY



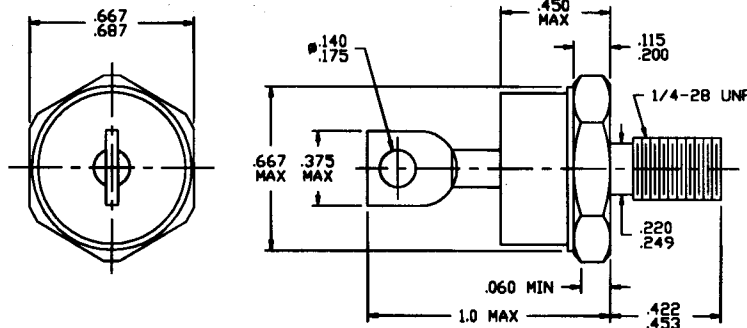
**SOLID STATE DEVICES, INC**

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## ELECTRICAL CHARACTERISTICS

CHARACTERISTICS	SYMBOL	MAXIMUM	UNIT
<b>Instantaneous Forward Voltage Drop</b> ( $I_F = 50 \text{ A dc}$ , $T_A = 25^\circ\text{C}$ , 300 $\mu\text{s}$ Pulse)	<b>VF</b>	0.90	Vdc
<b>Instantaneous Forward Voltage Drop</b> ( $I_F = 50 \text{ A dc}$ , $T_A = -55^\circ\text{C}$ , 300 $\mu\text{s}$ Pulse)	<b>VF</b>	1.0	Vdc
<b>Reverse Leakage Current</b> (Rated $V_R$ , $T_A = 25^\circ\text{C}$ , 300 $\mu\text{s}$ pulse minimum)	<b>IR</b>	250	$\mu\text{A}$
<b>Reverse Leakage Current</b> (Rated $V_R$ , $T_A = 100^\circ\text{C}$ , 300 $\mu\text{s}$ pulse minimum)	<b>IR</b>	20	mA
<b>Junction Capacitance</b> ( $V_R = 10 \text{ Vdc}$ , $T_A = 25^\circ\text{C}$ , $f = 1 \text{ MHz}$ )	<b>CJ</b>	400	pf
<b>Reverse Recovery Time</b> ( $I_F = 500 \text{ mA}$ , $I_R = 1 \text{ A}$ , $I_{RR} = 250 \text{ mA}$ , $T_A = 25^\circ\text{C}$ )	<b>trr</b>	50	nsec

## CASE OUTLINE: DO-5



Dimensions prior to solder dipping.

## TYPICAL OPERATING CURVES

$T_A = 25^\circ\text{C}$  Unless otherwise specified

